



Setting the Test Standard for Tomorrow

June 2026 | Nasdaq: AEHR

Aehr Test Systems Company Overview

Semiconductor Test & Burn-in for over 45 Years!

- Worldwide leader in wafer-level test and burn-in systems
- Unique full-wafer test and burn-in systems and contactors
- Technology leader in massively parallel and high-power test and burn-in systems

FOXXP



High Power Multi-Wafer
Test & Burn-In System

SONOMA



High Power
Test & Burn-In System

FOXCP



Single Wafer Stepping
Test & Burn-In System

TAH-E



Medium Power
Test & Burn-In System

AEHR
TEST SYSTEMS

Aehr Manufacturing Capacity

- State-of-the-art manufacturing facility located in Fremont, CA
- 50,000+ sq. foot facility
- Power and Infrastructure to support up to 400 wafers (tester Blades) and WaferPaks for Wafer Level Burn-in and 20 Package Level Burn-in Systems per month
- Manufacturing capabilities and quality control procedures have passed rigorous Tier 1 customer qualification processes



Aehr Fremont Production Floor



Aehr Test Systems Market Drivers

Need for cost-efficient wafer level, singulated die, and package level burn-in, stabilization, & testing is creating significant revenue opportunities for Aehr Test in the following key markets:

- **Artificial Intelligence Processors and Processing Infrastructure** driving explosive spend in data center processing, edge processors, communication infrastructure, and power conversion infrastructure which drives AI processors, memory, data storage, Silicon Photonics I/O, and power conversion semiconductors like Silicon Carbide & Gallium Nitride
- **Data Center Infrastructure and unstoppable growth in Data Storage** driving Silicon Photonics, Flash Memory Solid State Data Storage, and new Photonics Assisted Hard Disk Drive Storage
- **Heterogeneous Integration of semiconductors and 3D fabrication and stacking** driving technology and cost roadmaps pushing known good die with test and burn-in of device in wafer form prior to packaging
- **Electric Vehicle & Electrification of Transportation Infrastructure** driving motor control, charging infrastructure, and power conversion using Silicon Carbide & Gallium Nitride semiconductors
- **Electrification of the World's Power Infrastructure and Shift to Clean Energy** driving efficient and economical electrical power conversion using Silicon Carbide & Gallium Nitride semiconductors



AI Processor Package vs Wafer Level Burn-in Flow

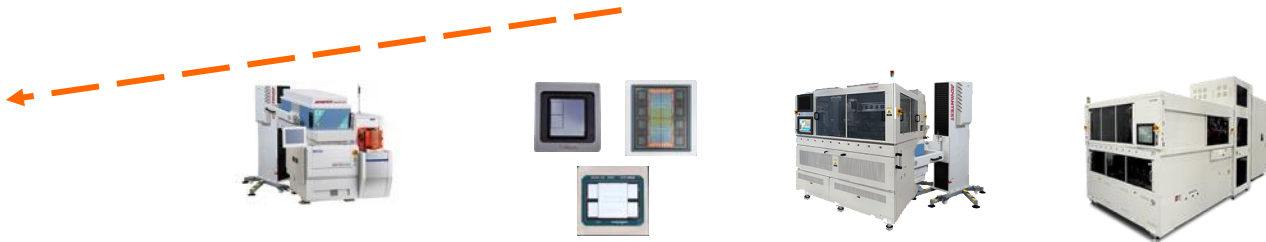
Package Level Burn-In Test Flow



Aehr Sonoma



Aehr FOX-XP



Wafer Level Burn-In Test Flow – High Quality Bare Die

Proprietary Wafer Level Enabling Technology

- Aehr's FOX-XP is capable of both functional burn-in and test solutions – leverages proprietary aligner and contactor technology
- Multi-wafer technology enables customers to achieve an overall decrease in test equipment cost and fab footprint – while increasing die yield and throughput

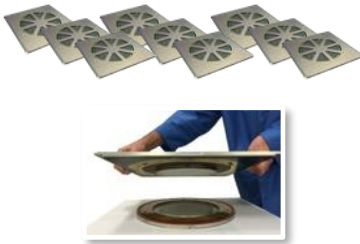
MULTI-WAFER TESTER



*FOX-XP Multi-Wafer
Test System*

- May be configured with up to 18 Blades, enabling 18 wafers to be tested in parallel – driving cost efficiency and throughput
- High performance thermal chucks allow uniform temperature control of the wafers
- Footprint similar to single wafer automated test equipment – reducing lab test space

CONTACTOR



FOX-XP WaferPaks

- Houses the wafer and distributes signals and power to the wafer itself
- The WaferPak contactor is capable of over 50,000 contacts in a single touchdown on up to 300mm wafers
- Consumable input into the test system driving recurring revenue from the installed base

ALIGNER



*FOX WaferPak
Aligner*

- Integral piece of test cell as it loads the wafer in the WaferPak at immense levels of precision
- By perfectly setting the wafer in a cartridge it ensures perfect contact
- Performs wafer alignment “offline” which eliminates the need for one wafer prober per wafer during long burn-in and test times

Aehr Wafer Level Test & Burn-in Patents



- WaferPak temperature control methods
- Vacuum & pressure-based WaferPaks
- Maintaining probe contact over temperature
- Electrical components in WaferPak
- Individual DUT power supplies
- Per Die Current Protection
- Redundant power supplies
- Portable WaferPaks
- And more . . .

FOX-XP Multi-Wafer Production Test & Burn-In System

- **9 / 18 wafer system high volume production**

- FOX-P blades configurable with same resource options as FOX-NP and FOX-CP blades
- Delivers up to 2,048 independent universal channels or 1,024 High current or high voltage channels per blade
- Delivers and dissipates up to 3.5kW of power and up to 4,000 amps to and from the wafer

- **Uses FOX compatible WaferPaks**

- Over 50,000 pin “probe cards”
- Very high compliance micro pogo pins and/or MEMS capability
- Test & burn-in temperatures to 150C
- Offline wafer alignment via AeHR proprietary WaferPak aligners



FOX-XP 18 Wafer Test & Burn-In System



FOX WaferPaks

FOX-XP with 18 Blades



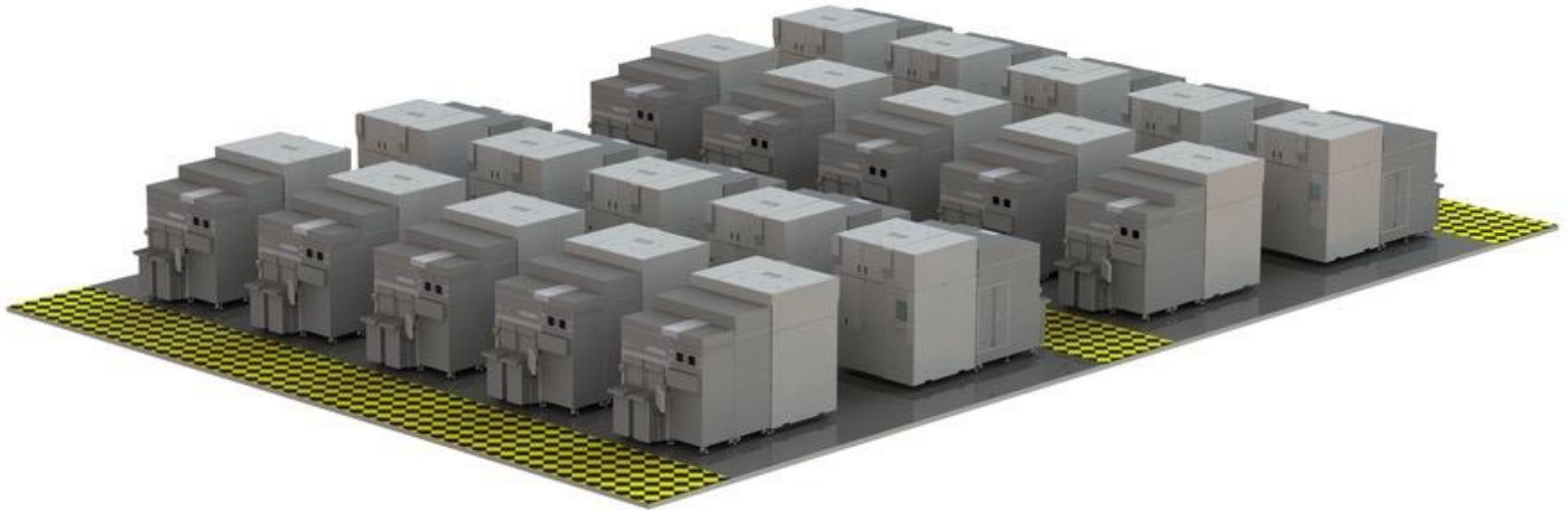
FOX-XP with Fully Automated WaferPak Aligner

- Fully automated FOX-XP System
- Provides customers fully hands-free operation up to lights out SECS/GEM factory automation and integration
- Configurable for 300mm to 100mm wafers using industry standard load ports
- Optical wafer to WaferPak alignment up to 150C test/burn-in temperatures



FOX-XP with Integrated WaferPak Aligner
(Configured for 300mm AI Processor Wafers)

FOX-XP with Integrated WaferPak Aligners Floorplan



360 Wafer Capacity Footprint with full SECS/GEM E84 Automation

FOX-NP NPI and Engineering Test & Burn-In System

- **Dual wafer system for new product introduction, engineering and low volume production**

- FOX-P blades configurable with same resource options as FOX-XP and FOX-CP blades up to 3.5 kW per blade
- Delivers up to 2,048 independent universal channels or 1,024 high current or high voltage channels per blade
- Integrated standard 20C to 150C thermal control unit
- Small lab footprint
- Excellent for program development, process monitoring, new product introduction, stress test, HALT, HTOL, and low volume production test and burn-in



FOX-NP Dual Wafer Test & Burn-In System

- **Uses FOX compatible WaferPaks**

- Over 50,000 pin “probe cards”
- Very high compliance micro pogo pins and/or MEMS capability
- Offline wafer alignment via Aehr proprietary WaferPak aligners

- **Uses FOX compatible DiePaks**

- Singulated die, modules, or packages
- Exceptional thermal density performance and uniformity via conductive thermal transfer to thermal plates



FOX WaferPak & DiePak Contactors

FOX WaferPak Contactor

- **Extremely simple contactor “Probe Card”**

- No backside stiffener
- No interposer required
- No expensive tester interconnects
- Simple per-pin repairability
- Easy to manufacture in high volume

- **Enabling architecture for low cost of test**

- One aligner shared across many wafer positions
- Supports stepping across wafer for high die count wafers
- “Rugged” design allows movement of aligned wafers
- Allows wide test temperatures after alignment (single probe mark)

- **Enabling architecture for small footprint**

- Allows high density stacking (18 wafers in a single column)
- Full functional tester and interface within a 3.4” pitch
- Conductive thermal chuck per position within 3.4” pitch

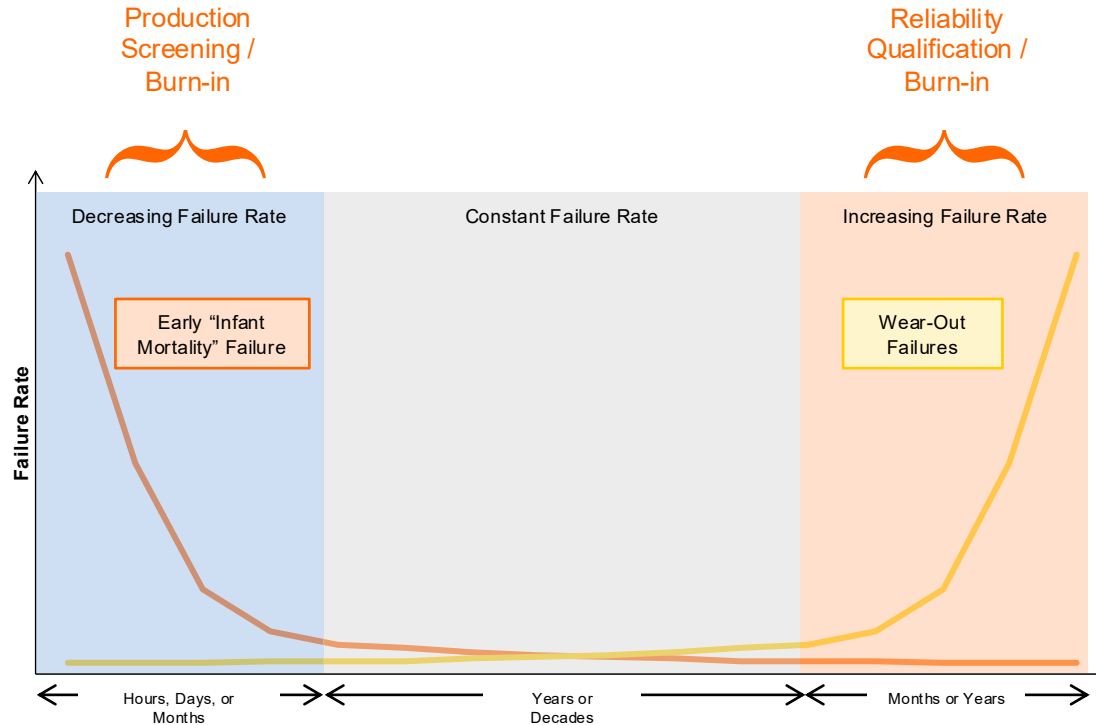


FOX WaferPak Contactor



Manual Insertion into FOX-XP

Burn-in Testing – The Bathtub Curve



- **Production Burn-in:** semiconductor components are subjected to elevated voltages and temperatures for a duration of time (2 – 48 hours) to screen for reliability and early failure in production before shipping to customers
- **Reliability Qualification Burn-in:** semiconductor components subjected to elevated voltage and temperatures for 1000 hours to validate and meet industry standards for long term reliability via High Temperature Operating Life (HTOL) tests

AI Accelerator/Processor PLBI Momentum

- High-power package level test & burn-in for production, reliability qualification, and life-time tests
- Up to 88 processors with independent test resources and high-power liquid cooling per device
- Qualification and Production configurations
- Shipping in volume with multiple systems installed at most test houses today



SONOMA

High Power Test &
Burn-in System

AEHR
TEST SYSTEMS

AI Accelerator/Processor PLBI Momentum

- AeHR Sonoma platform has the largest installed base of ultra-high-power burn-in systems for High Temperature Operating Life (HTOL) used for AI processors at test houses around the world.
- Successfully captured the production system capacity needs from one of the largest Hyperscalers in the world on the first AI Accelerator that they are doing production burn-in screening on. They have purchased a significant number of Sonoma systems, already installed in Asia at a leading test contract manufacturer, and are forecasting a significant ramp over the next several years.
- Recently won multiple new HTOL reliability burn-in deals for AI processors to be used at world leading test houses that have AeHR Sonoma systems and plan to order additional systems.
- One of these HTOL applications is already slated for production burn-in that will drive large numbers of systems in Asia at test houses and AeHR has already been selected for production burn-in of these processors



SONOMA

High Power Test &
Burn-in System

AEHR
TEST SYSTEMS

Sonoma with Automated Loader / Unloader



AI Accelerator/Processor WLBI Momentum

- Aehr worked with and successfully captured the first production orders from an AI Accelerator company to move their AI processor system level test and burn-in to wafer level on the Aehr FOX-XP system. **Recently announced production capacity to drive incremental systems and WaferPaks and also move to fully automated 300mm wafer handling**
- Announced paid-for production WLBI evaluation from a leading AI processor supplier which is **currently in development with very positive results completed in the last quarter**
- **Multiple additional potential customers have approached Aehr to demonstrate WLBI on their AI accelerator processors and CPUs**
- **Recently announced partnership with ISE/ASE** the worlds largest semiconductor Out-Sourced Assembly and Test House (OSAT) to comarket and proliferate WLBI in addition to PLBI for AI processors



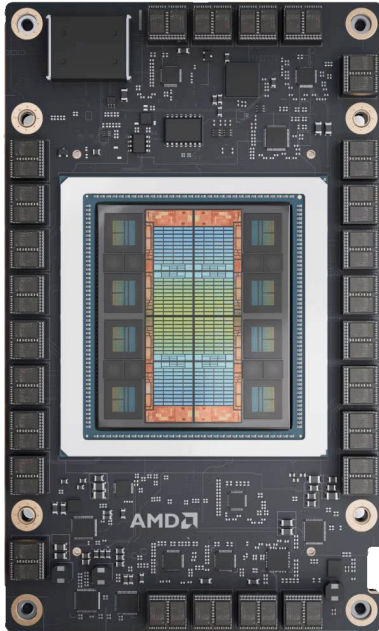
FOXXP

**High Power Multi-Wafer
Test & Burn-In System**
*(Shown with Integrated
WaferPak Aligner)*

AEHR
TEST SYSTEMS

AI Accelerator Example of Multi-Chip Packaging

AMD Instinct™ MI325X Accelerator



- Multiple Compute Chiplets
- 8 12-Die HBM3 DRAM Stacks
- Single OAM Substrate
- Roadmap for new Chiplet Architecture Accelerators each year from 2023 to 2026
- 8 MI325X Cluster:



Optical I/O is Here...

- "Spectrum-X Ethernet Photonics sets a new standard for scalable, energy-efficient Ethernet networks that power million-GPU AI clusters." – NVIDIA, March 2026
- "Intel® Optical Compute Interconnect (OCI) is a new class of optical connectivity devices, delivering multi-terabit per second solutions with the reach and energy efficiency required to dramatically scale next-generation compute platforms and architectures, supporting the exponential growth of AI infrastructure." – Intel, May 2026
- "Our expanded partnership with NVIDIA reflects the growing importance of high-speed connectivity, optical interconnect and accelerated infrastructure in scaling AI." – Marvell, March 2026
- "The Enosemi team will help AMD immediately scale our ability to support and develop a variety of photonics and co-packaged optics solutions across next-generation AI systems." –AMD, May 2025



Flash Memory WLBI Opportunity

- Aehr has been engaged with multiple Flash memory companies related to our FOX wafer level test and burn-in systems for their high-volume production
- Aehr recently completed the first phase showing full-wafer contact and test/burn-in of their 300mm NAND flash wafer used to evaluate the FOX-XP system with our proprietary WaferPak full wafer contactors for their new HBF flash devices in production
- This application is for 100% test and burn-in of their High Bandwidth Flash memory devices to be used in mission critical applications such as AI LLM, inference, and for automotive and industrial robotics applications
- We see the NAND Flash market as a key new market opportunity for our systems and WaferPaks, with long term potential to also move into DRAM wafer level test and burn-in



FOX XP

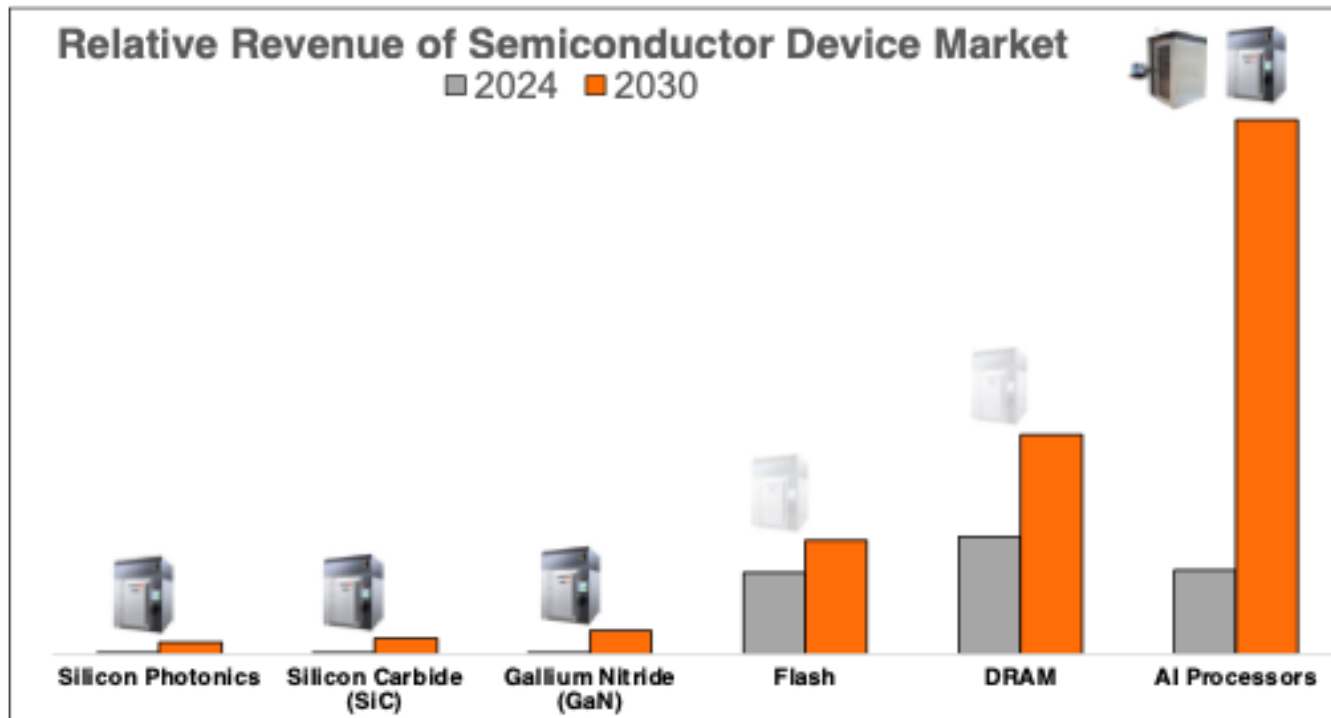
**High Power Multi-Wafer
Test & Burn-In System**
*(Shown with Integrated
WaferPak Aligner)*

AEHR
TEST SYSTEMS

Relative Size of Targeted Semiconductor Device Markets

These are relative annual revenues of these semiconductor devices.

Historically, annual capital spend on test ranges from 2% to 5% of the device annual revenue.



Estimated market sizes based on third party sources and AeHR estimates.

Testing without Compromise

Reliability, Stress, and DFT Testing without compromise

- Solutions for **packaged parts, modules, panels, or wafers** allow testing at optimal process point
- **Confirm** which devices received desired test with **per device measurements, monitoring, & feedback**
- **100% traceability** with die location (wafer) or device ID read back (module) and electronic tracking ensures knowledge of “good” devices
- Thermal range, uniformity, and capacity permit **reduced test times & confidence** in target **test conditions**
- Vast system resources allow for minimal sharing (**higher sample size, higher yields, fewer hostage failures**)
- **Economical solutions and customizations** allow required testing to be performed at the **lowest cost**



Setting the Test Standard for Tomorrow

June 2026 | Nasdaq: AEHR